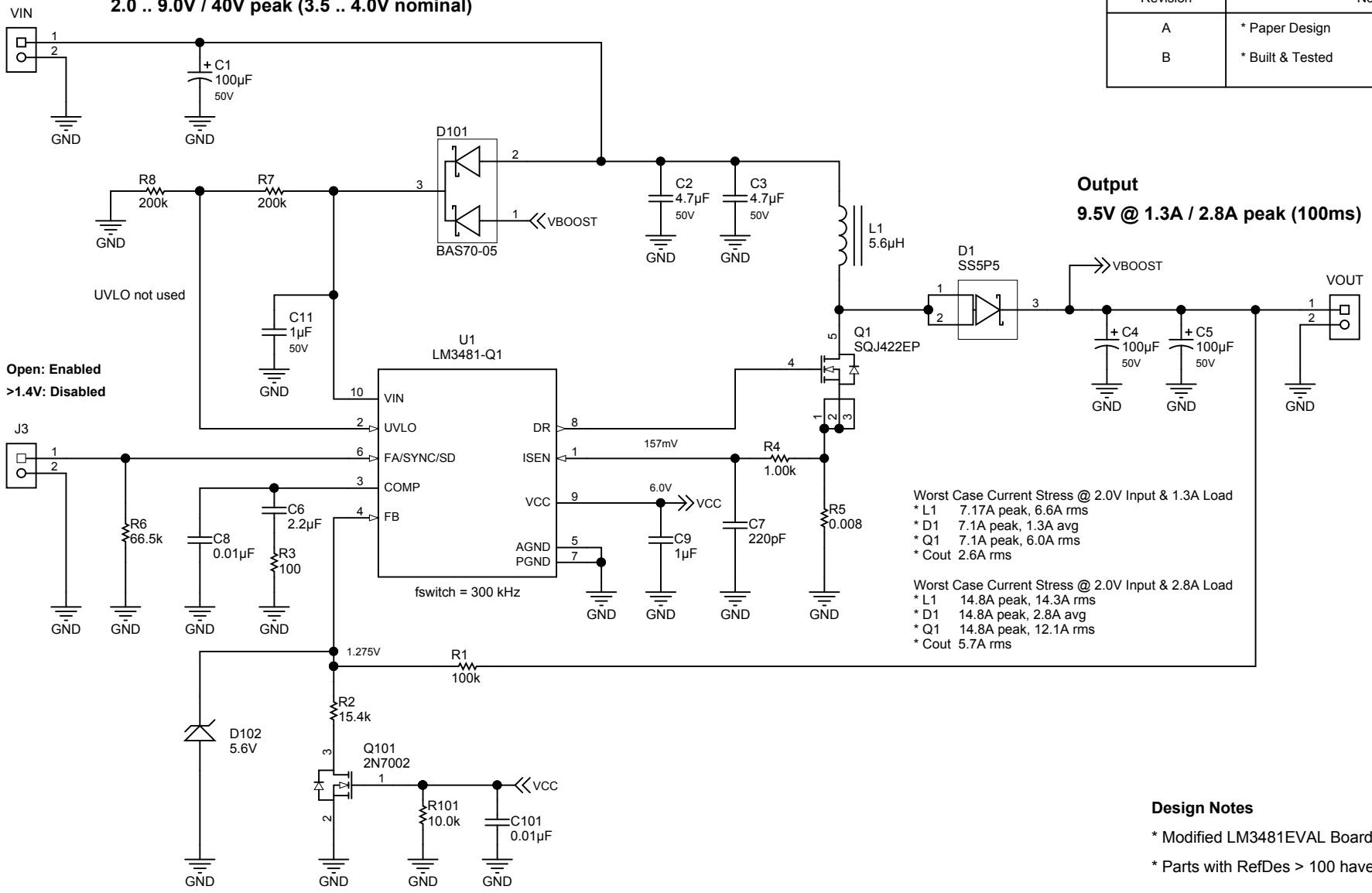

Revision History	
Revision	Notes
A	* Paper Design
B	* Built & Tested

Design Notes

* Modified LM3481EVAL Board
* Parts with RefDes > 100 have no footprint on PCB

Number: PMP11784	Rev: B	Designed for: Public Release	Mod. Date: 1/12/2016
		Project Title: Automotive Boost	
		Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: [No Variations]	Sheet: 1 of 1
Drawn By:		File: PMP11784RevB.SchDoc	Size: A4
Engineer: Matthias Ulmann		Contact: http://www.ti.com/support	

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